



# PMEG3002EJ

30 V, 200 mA low VF Schottky barrier rectifier

30 September 2025

Product data sheet

## 1. General description

Planar Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a SOD323F (SC-90) small and flat lead Surface-Mounted Device (SMD) plastic package.

## 2. Features and benefits

- Average forward current:  $I_{F(AV)} \leq 0.2$  A
- Reverse voltage:  $V_R \leq 30$  V
- Low forward voltage
- Small and flat lead SMD plastic package

## 3. Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch Mode Power Supply (SMPS)
- Reverse polarity protection
- Ultra high-speed switching
- Low power consumption applications

## 4. Quick reference data



Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; $f = 20$ kHz; square wave; $T_{amb} \leq 135$ °C	-	-	0.2	A
		$\delta = 0.5$ ; $f = 20$ kHz; square wave; $T_{sp} \leq 145$ °C	-	-	0.2	A
$V_R$	reverse voltage	$T_j = 25$ °C	-	-	30	V
$V_F$	forward voltage	$I_F = 200$ mA; $T_j = 25$ °C	-	420	480	mV
$I_R$	reverse current	$V_R = 30$ V; $T_j = 25$ °C	-	10	40	μA

[1] Device mounted on a ceramic Printed-Circuit Board (PCB),  $Al_2O_3$ , standard footprint.

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode[1]	 SC-90 (SOD323F)	 sym001
2	A	anode		

[1] The marking bar indicates the cathode.

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
<a href="#">PMEG3002EJ</a>	SC-90	plastic, surface-mounted package; 2 leads; 1.7 mm x 1.25 mm x 0.7 mm body	<a href="#">SOD323F</a>

7. Marking

Table 4. Marking codes

Type number	Marking code
PMEG3002EJ	1M

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
$V_R$	reverse voltage	$T_j = 25\text{ }^{\circ}\text{C}$		-	30	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; $f = 20\text{ kHz}$ ; square wave; $T_{amb} \leq 135\text{ }^{\circ}\text{C}$	<a href="#">[1]</a>	-	0.2	A
		$\delta = 0.5$ ; $f = 20\text{ kHz}$ ; square wave; $T_{sp} \leq 145\text{ }^{\circ}\text{C}$		-	0.2	A
$I_{FRM}$	repetitive peak forward current	$t_p \leq 1\text{ ms}$ ; $\delta \leq 0.25$		-	2.6	A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 8\text{ ms}$ ; square wave; $T_j = 25\text{ }^{\circ}\text{C}$ prior to surge; $T_{j(init)} = 25\text{ }^{\circ}\text{C}$		-	2.75	A
$P_{tot}$	total power dissipation	$T_{amb} \leq 25\text{ }^{\circ}\text{C}$	<a href="#">[2]</a> <a href="#">[3]</a>	-	385	mW
			<a href="#">[2]</a> <a href="#">[4]</a>	-	695	mW
			<a href="#">[5]</a> <a href="#">[2]</a>	-	1.045	W
$T_j$	junction temperature			-	150	$^{\circ}\text{C}$
$T_{amb}$	ambient temperature			-55	150	$^{\circ}\text{C}$
$T_{stg}$	storage temperature			-65	150	$^{\circ}\text{C}$

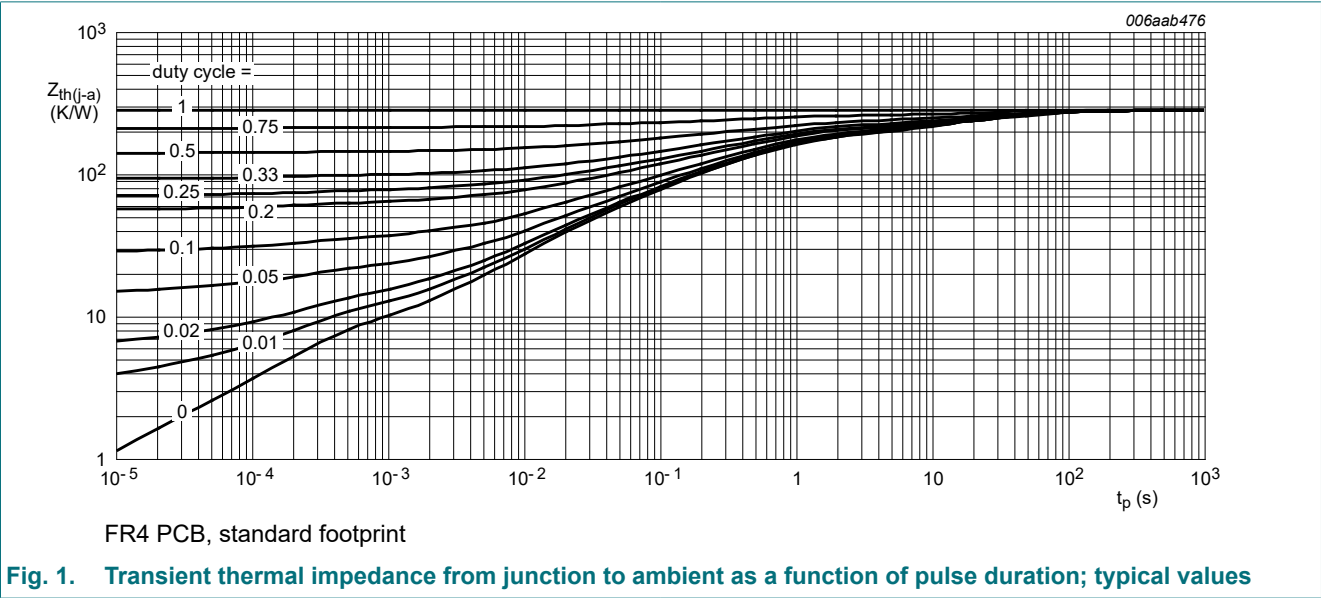
- [1] Device mounted on a ceramic Printed-Circuit Board (PCB), Al<sub>2</sub>O<sub>3</sub>, standard footprint.
- [2] Reflow soldering is the only recommended soldering method.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.
- [5] Device mounted on a ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint.

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] [2] [3]	-	-	325	K/W
			[1] [2] [4]	-	-	180	K/W
			[1] [2] [5]	-	-	120	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[6]	-	-	25	K/W

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses  $P_R$  are a significant part of the total power losses.
- [2] Reflow soldering is the only recommended soldering method.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.
- [5] Device mounted on a ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint.
- [6] Soldering point of cathode tab.



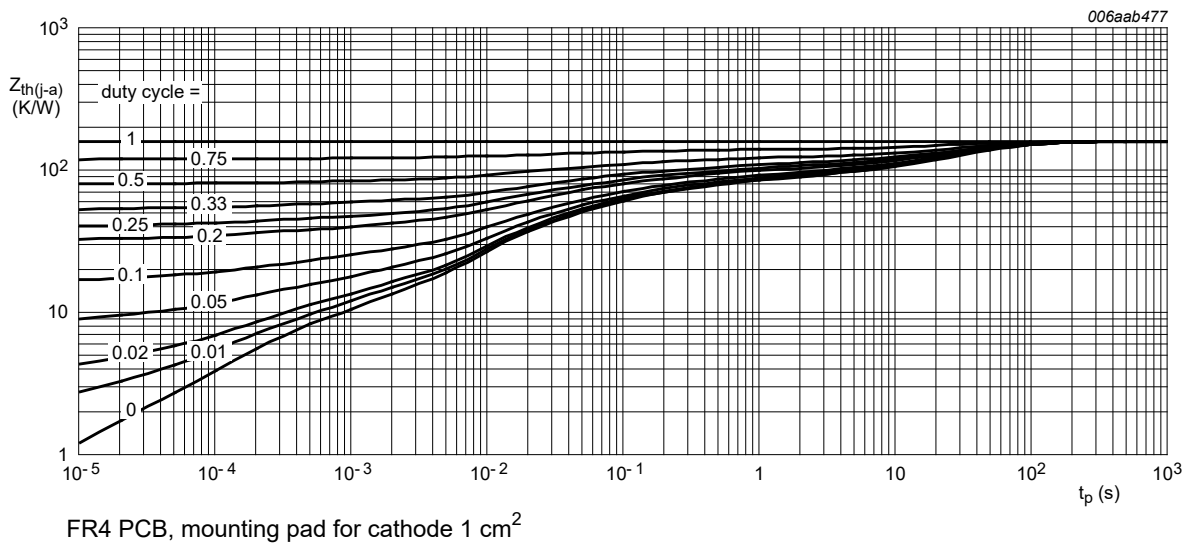


Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

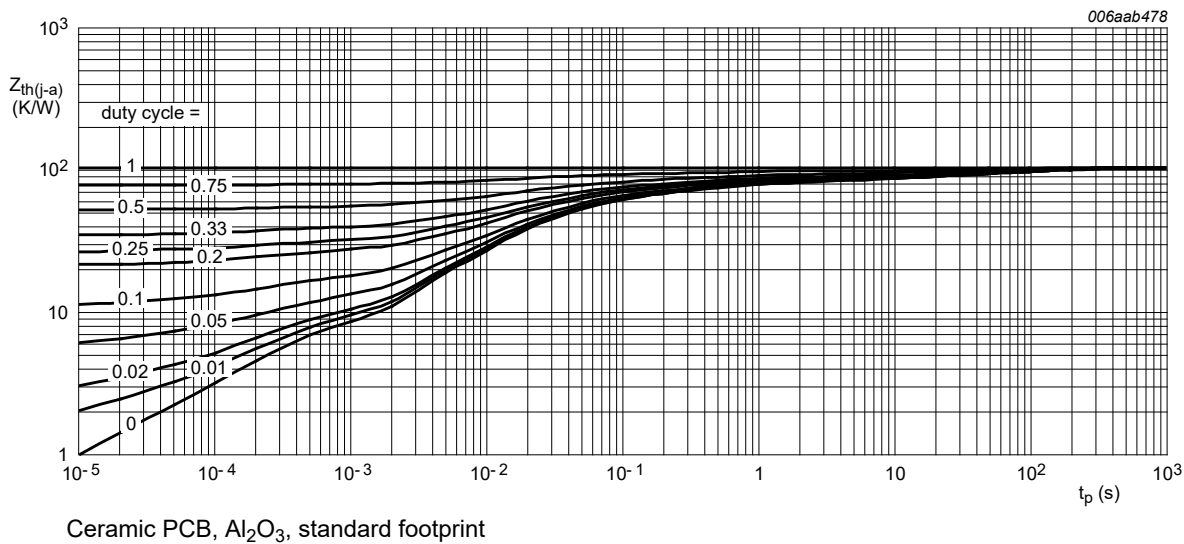
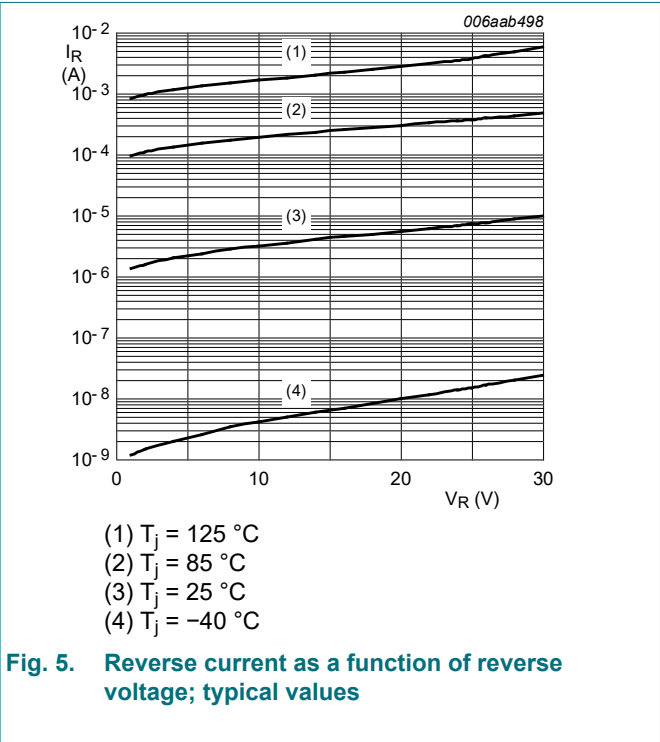
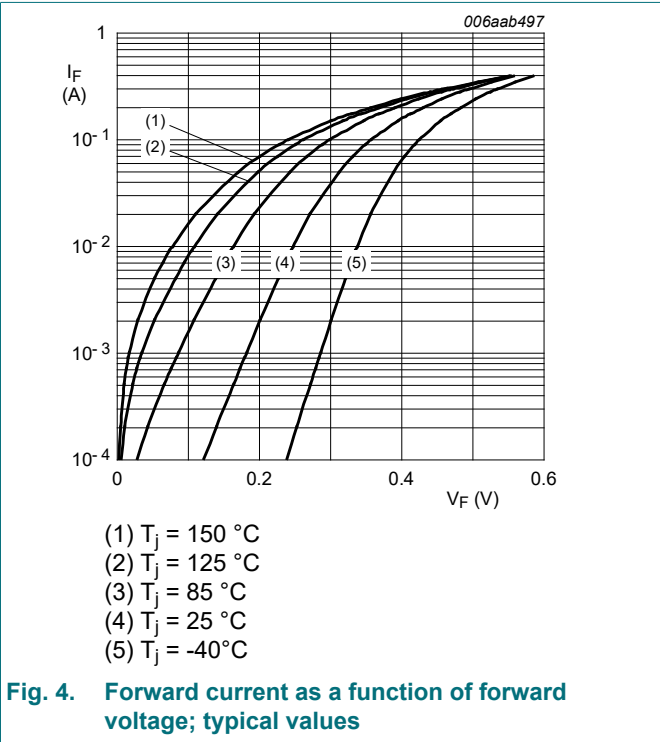


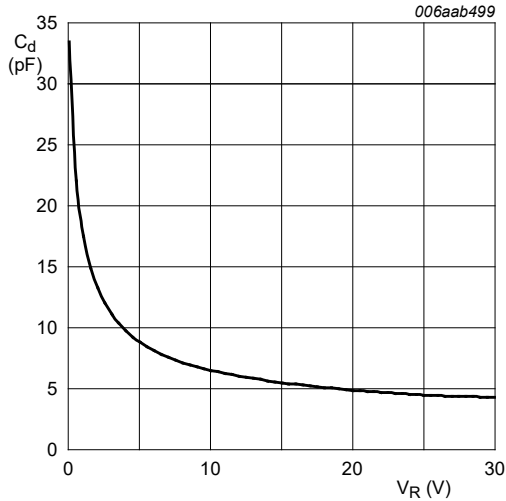
Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

Table 7. Characteristics

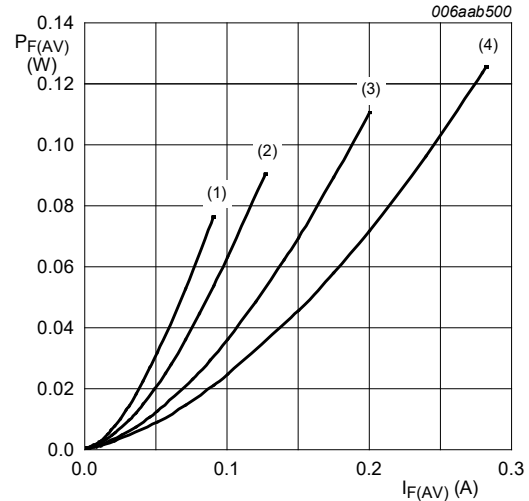
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 0.1 mA; T <sub>j</sub> = 25 °C	-	130	190	mV
		I <sub>F</sub> = 1 mA; T <sub>j</sub> = 25 °C	-	190	250	mV
		I <sub>F</sub> = 10 mA; T <sub>j</sub> = 25 °C	-	250	300	mV
		I <sub>F</sub> = 100 mA; T <sub>j</sub> = 25 °C	-	355	400	mV
		I <sub>F</sub> = 200 mA; T <sub>j</sub> = 25 °C	-	420	480	mV
I <sub>R</sub>	reverse current	V <sub>R</sub> = 10 V; T <sub>j</sub> = 25 °C	-	2.5	10	μA
		V <sub>R</sub> = 30 V; T <sub>j</sub> = 25 °C	-	10	40	μA
C <sub>d</sub>	diode capacitance	V <sub>R</sub> = 1 V; f = 1 MHz; T <sub>j</sub> = 25 °C	-	18	-	pF
		V <sub>R</sub> = 10 V; f = 1 MHz; T <sub>j</sub> = 25 °C	-	7	-	pF
t <sub>rr</sub>	reverse recovery time	When switched from I <sub>F</sub> = 10 mA to I <sub>R</sub> = 10 mA; R <sub>L</sub> = 100 Ω; measured at I <sub>R</sub> = 1 mA.; T <sub>j</sub> = 25 °C	-	5	-	ns





$f = 1 \text{ MHz}$ ;  $T_{\text{amb}} = 25 \text{ }^{\circ}\text{C}$

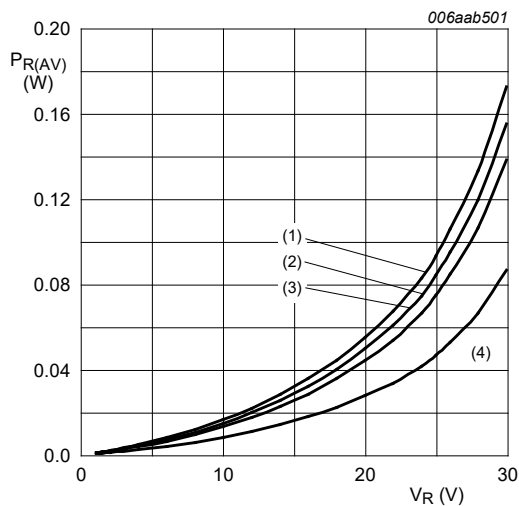
**Fig. 6.** Diode capacitance as a function of reverse voltage; typical values



$T_j = 150 \text{ }^{\circ}\text{C}$

- (1)  $\delta = 0.1$
- (2)  $\delta = 0.2$
- (3)  $\delta = 0.5$
- (4)  $\delta = 1$

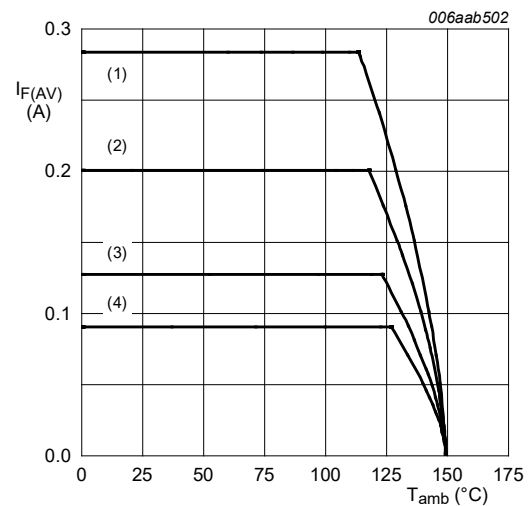
**Fig. 7.** Average forward power dissipation as a function of average forward current; typical values



$T_j = 125 \text{ }^{\circ}\text{C}$

- (1)  $\delta = 1$
- (2)  $\delta = 0.9$
- (3)  $\delta = 0.8$
- (4)  $\delta = 0.5$

**Fig. 8.** Average reverse power dissipation as a function of reverse voltage; typical values

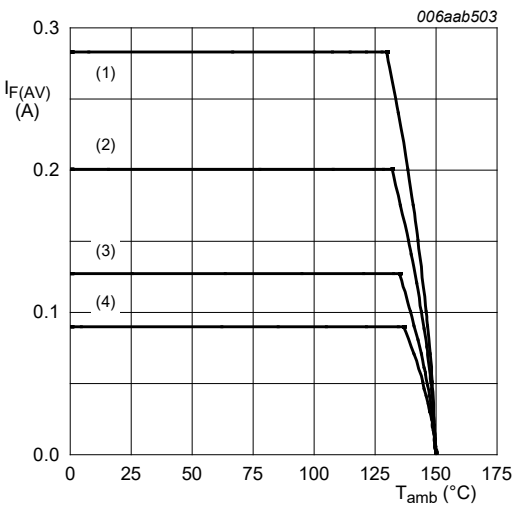


FR4 PCB, standard footprint

$T_j = 150 \text{ }^{\circ}\text{C}$

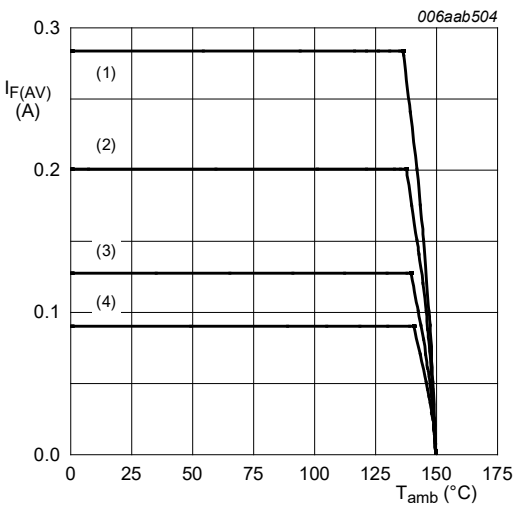
- (1)  $\delta = 1$ ; DC
- (2)  $\delta = 0.5$ ;  $f = 20 \text{ kHz}$
- (3)  $\delta = 0.2$ ;  $f = 20 \text{ kHz}$
- (4)  $\delta = 0.1$ ;  $f = 20 \text{ kHz}$

**Fig. 9.** Average forward current as a function of ambient temperature; typical values



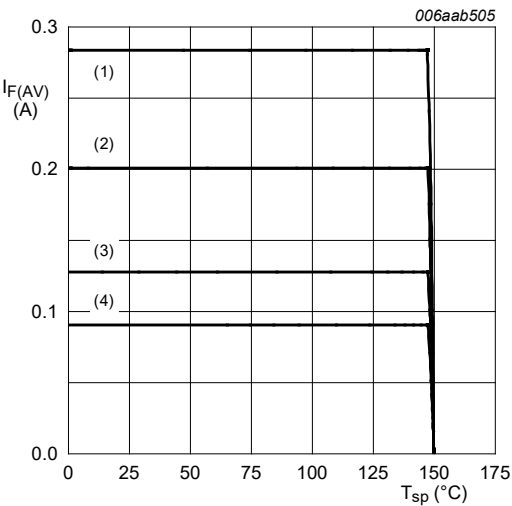
FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>  
 $T_j = 150$  °C  
(1)  $\delta = 1$ ; DC  
(2)  $\delta = 0.5$ ;  $f = 20$  kHz  
(3)  $\delta = 0.2$ ;  $f = 20$  kHz  
(4)  $\delta = 0.1$ ;  $f = 20$  kHz

Fig. 10. Average forward current as a function of ambient temperature; typical values



Ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint  
 $T_j = 150$  °C  
(1)  $\delta = 1$ ; DC  
(2)  $\delta = 0.5$ ;  $f = 20$  kHz  
(3)  $\delta = 0.2$ ;  $f = 20$  kHz  
(4)  $\delta = 0.1$ ;  $f = 20$  kHz

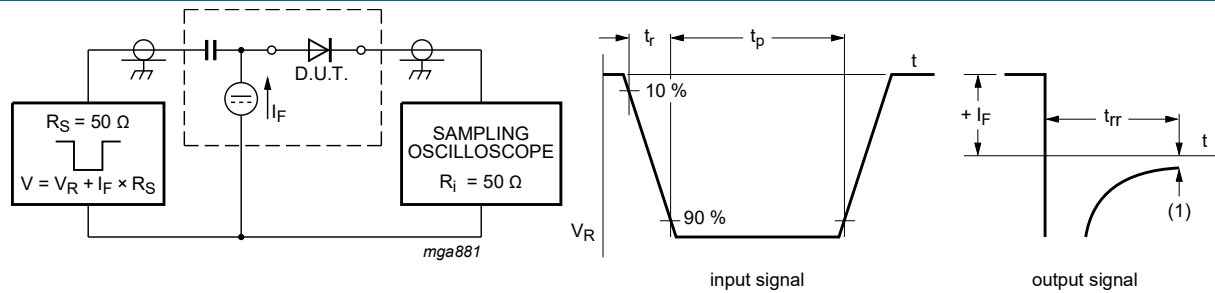
Fig. 11. Average forward current as a function of ambient temperature; typical values



$T_j = 150$  °C  
(1)  $\delta = 1$ ; DC  
(2)  $\delta = 0.5$ ;  $f = 20$  kHz  
(3)  $\delta = 0.2$ ;  $f = 20$  kHz  
(4)  $\delta = 0.1$ ;  $f = 20$  kHz

Fig. 12. Average forward current as a function of solder point temperature; typical values

## 11. Test information

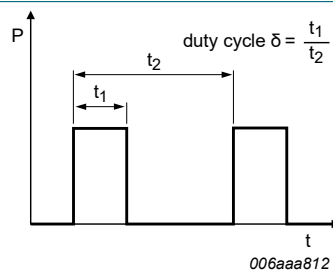


(1)  $I_R = 1 \text{ mA}$

Input signal: reverse pulse rise time  $t_r = 0.6 \text{ ns}$ ; reverse voltage pulse duration  $t_p = 100 \text{ ns}$ ; duty cycle  $\delta = 0.05$

Oscilloscope rise time  $t_r = 0.35 \text{ ns}$

**Fig. 13. Reverse recovery time: test circuit and waveforms**



**Fig. 14. Duty cycle definition**

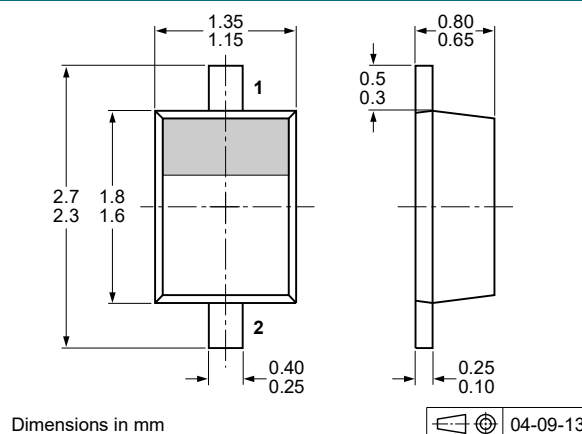
The current ratings for the typical waveforms are calculated according to the equations:

$$I_{F(AV)} = I_M \times \delta \text{ with } I_M \text{ defined as peak current}$$

$$I_{RMS} = I_{F(AV)} \text{ at DC}$$

$$I_{RMS} = I_M \times \sqrt{\delta} \text{ with } I_{RMS} \text{ defined as RMS current}$$

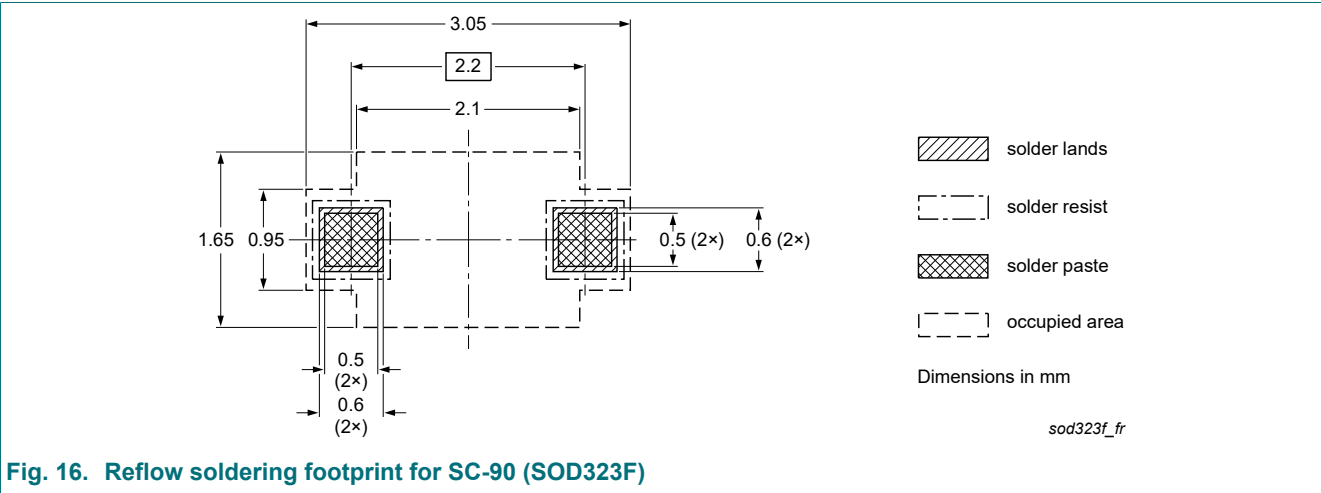
## 12. Package outline



**Fig. 15. Package outline SC-90 (SOD323F)**



13. Soldering



14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMEG3002EJ v.3	20250930	Product data sheet	-	PMEG3002EJ v.2
Modifications:	<ul style="list-style-type: none"><li>Product(s) changed to non-automotive qualification. Please refer to nexperia.com for automotive (-Q) product alternative(s).</li></ul>			
PMEG3002EJ v.2	20231101	Product data sheet	-	PMEG3002EJ v.1
PMEG3002EJ v.1	20090515	Product data sheet	-	-

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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